

C3535U-UNL1

High Power UV LED

Introduction

The C3535U-UNL1 Series LED from TSLC brings industry leading technology to the UV lighting market with its high reliability and performance. With a ceramic substrate and a 125 degree viewing angle primary optic, the C3535U-UNL1 is ideal for all UV curing and general UV applications.

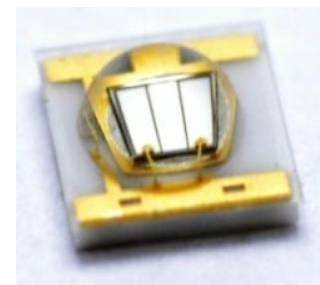


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RoHS Compliant

Characteristics

Absolute Maximum Ratings ($T_j=25^{\circ}\text{C}$)

Parameter	Rating
	UV Series
DC Forward Current (mA)	800 mA
LED Junction Temperature	150 $^{\circ}\text{C}$
LED Operating Temperature	-40 $^{\circ}\text{C}$ ~85 $^{\circ}\text{C}$
Storage Temperature	-40 $^{\circ}\text{C}$ ~125 $^{\circ}\text{C}$
Soldering Temperature	Max. 260 $^{\circ}\text{C}$ / Max. 10sec. (JEDEC 020c)
ESD Sensitivity	2,000 V HBM (JESD-22A-114-B)
Reverse Voltage	Not designed to be driven in reverse bias ($V_R \leq 5\text{V}$)
Preconditioning	Acc. to JEDEC Level 2

General Characteristics at 350mA

Part number	Color	Peak Wavelength λ_p		$2\theta_{1/2}$	Temperature Coefficient of V_f (mV/ $^{\circ}\text{C}$)	Thermal Resistance Junction to Pad ($^{\circ}\text{C}/\text{W}$)
		Min	Max		$\Delta V_f / \Delta T_j$	RO_{J-L}
C3535U-UNL1-A1G11H	U40	380	390	125	-2~-4	8
	U50	390	400	125	-2~-4	8
	U60	400	410	125	-2~-4	8
	U70	410	420	125	-2~-4	8

Notes:

- The peak wavelength is measured with an accuracy of $\pm 1\text{nm}$
- Minimum and maximum value refers to the limits and set up of TSLC testers. All other measurement data are defined as long-term production mean values and are only given for reference.
- A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system. Life support devices or systems are intended (i) to be implanted in the human body, or (ii) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered. Components used as a critical component must be approved in writing by TSLC.
- These devices emit high intensity UV/NUV light. Necessary precautions must be taken during operation. Do not look directly into the light or look through the optical system when in operation. Protective eyewear should be worn at all times during operation.
- Lens discoloration may occur with prolonged exposure to UV/NUV light. Lens material will need to be tested for UV/NUV light compatibility and durability.
- Always follow thermal design recommendations in this document.

Caution: Users are requested to comply with the laws and public regulations concerning safety.



Radiometric Power and Forward Voltage ($T_j=25^\circ\text{C}$)

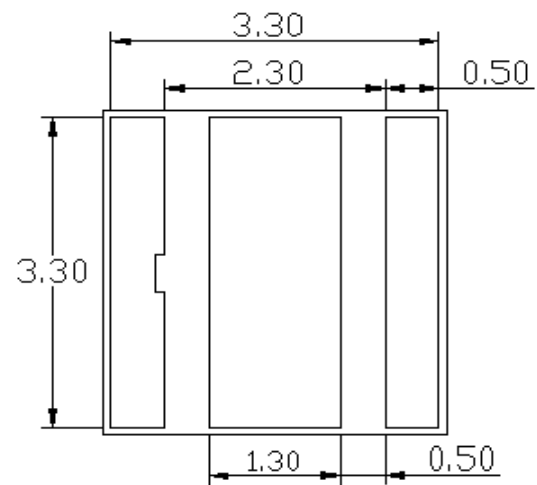
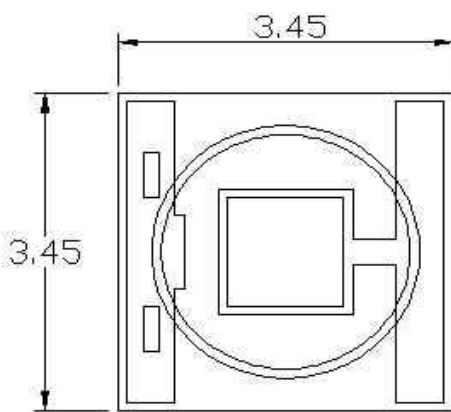
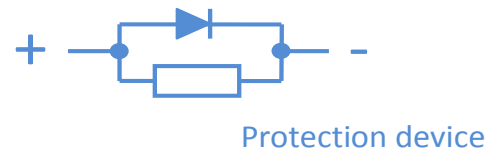
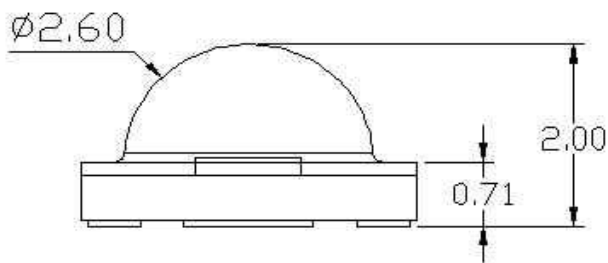
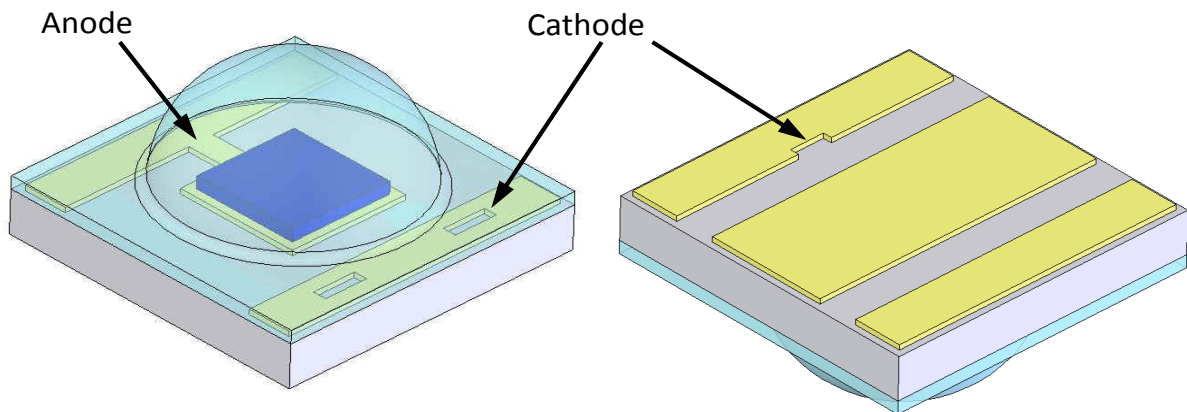
Part number	Color	Performance at Test Current (350mA)					Performance at 700mA
		Group	Radiometric Power (mW)		VF		Calculated Radiometric Power* (mW)
			Min	Max	Min	Max	
C3535U-UNL1-A1G11H	U40 (380-390nm)	ND5	360	400	3	4	648
		NE1	400	440	3	4	720
		NE2	440	480	3	4	792
	U50 (390-400nm)	NE1	400	440	3	4	720
		NE2	440	480	3	4	792
		NE3	480	520	3	4	864
	U60 (400-410nm)	NE2	440	480	3	4	792
		NE3	480	520	3	4	864
		NE4	520	560	3	4	936
	U70 (410-420nm)	NE2	440	480	3	4	792
		NE3	480	520	3	4	864
		NE4	520	560	3	4	936

Note: 1. Radiometric power is measured with an accuracy of $\pm 10\%$

2. The forward voltage is measured with an accuracy of $\pm 0.2\text{V}$

* Calculated values are for reference only.

Mechanical Dimensions



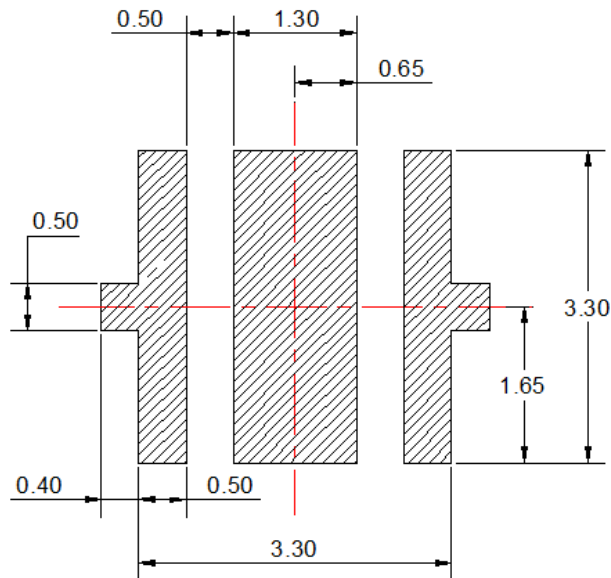
Notes :

1. Drawing is not to scale
2. All dimensions are in millimeter
3. Dimensions are $\pm 0.13\text{mm}$ unless otherwise indicated

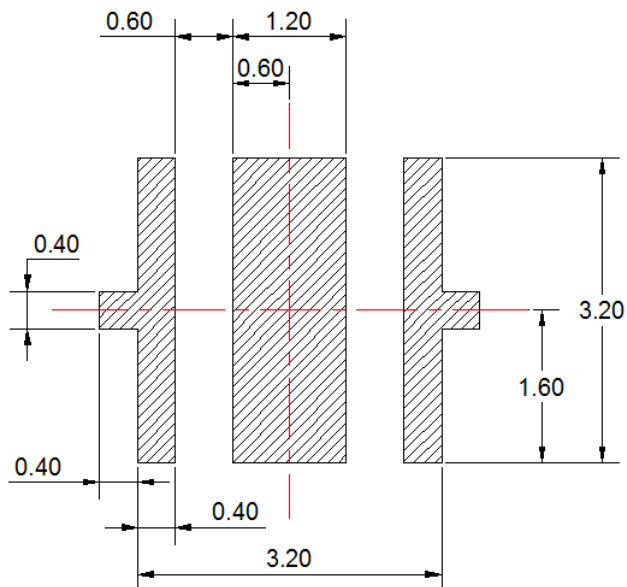


Recommended Solder Pad Design

Recommended Soldering Pad Design



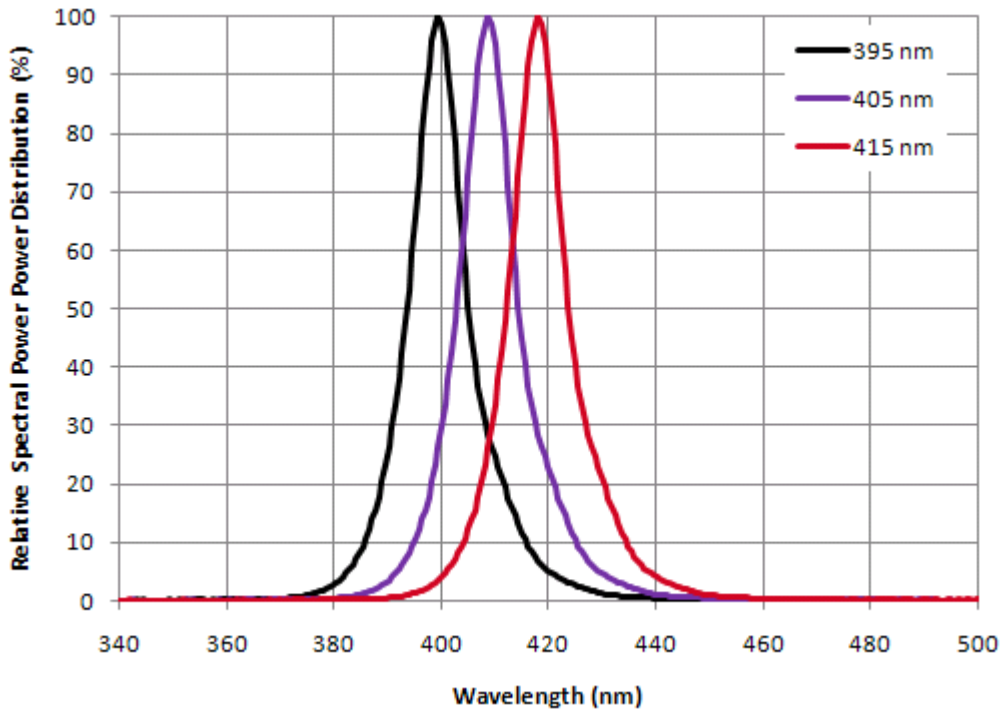
Recommended Stencil Pattern Design (Marked Area is Opening)



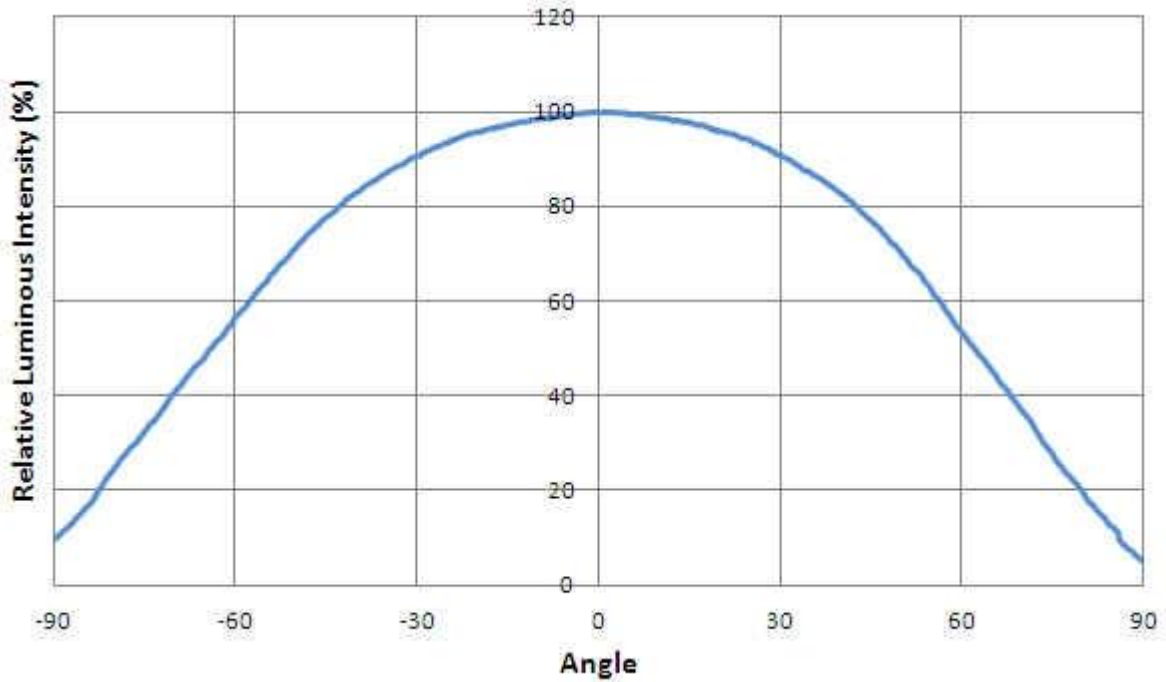
Notes :

1. Drawing is not to scale
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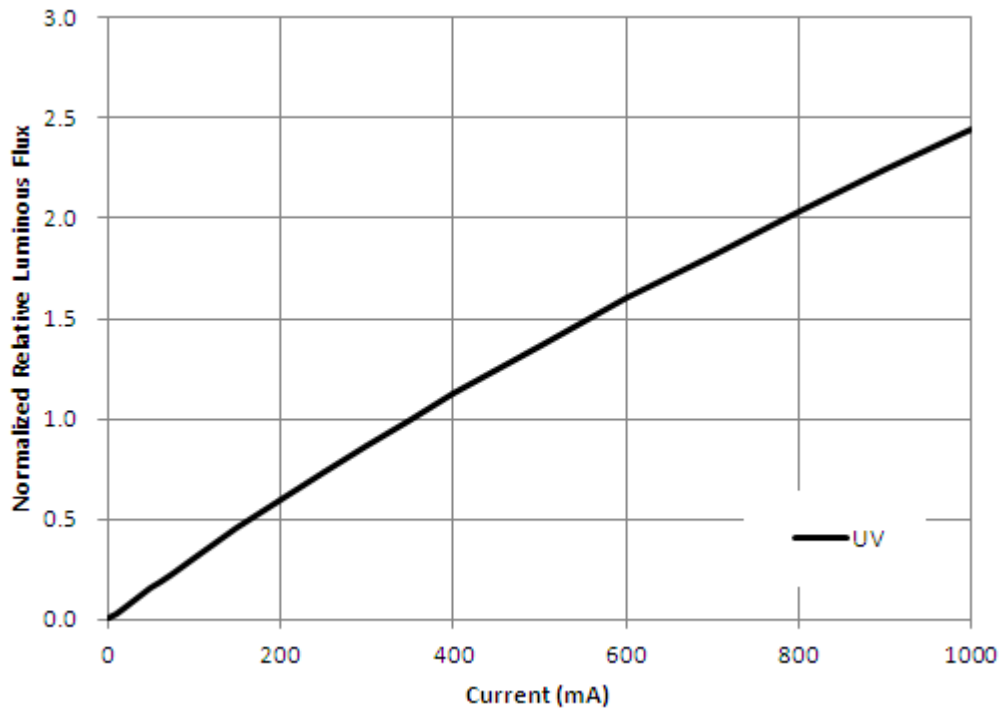
Relative Spectral Power Distribution, $T_j=25^\circ\text{C}$



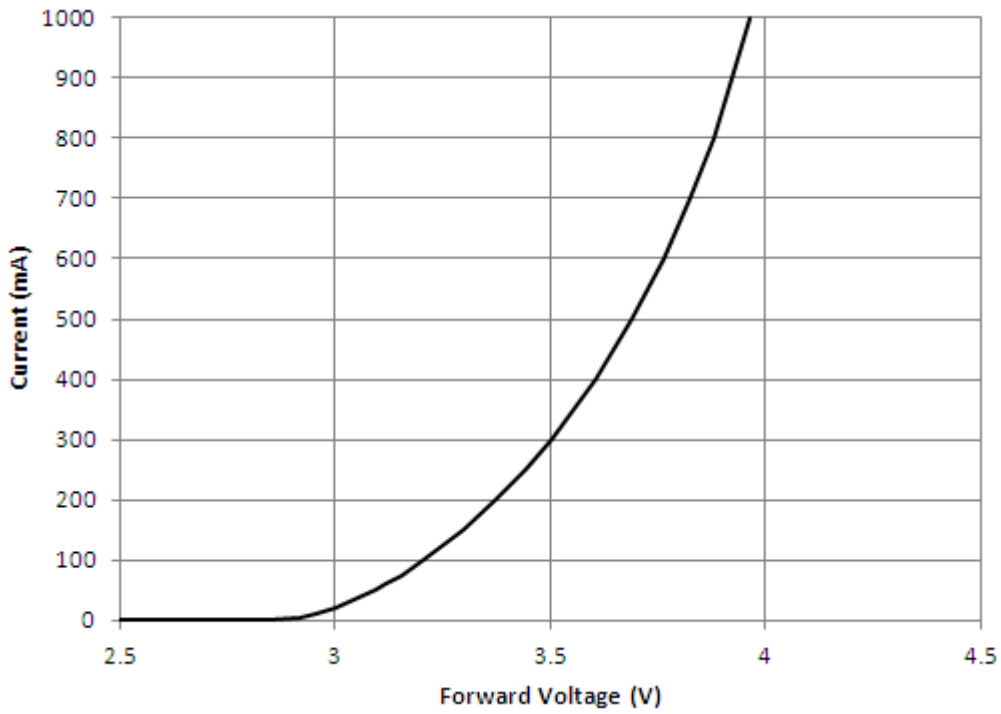
Typical Spatial Radiation Pattern



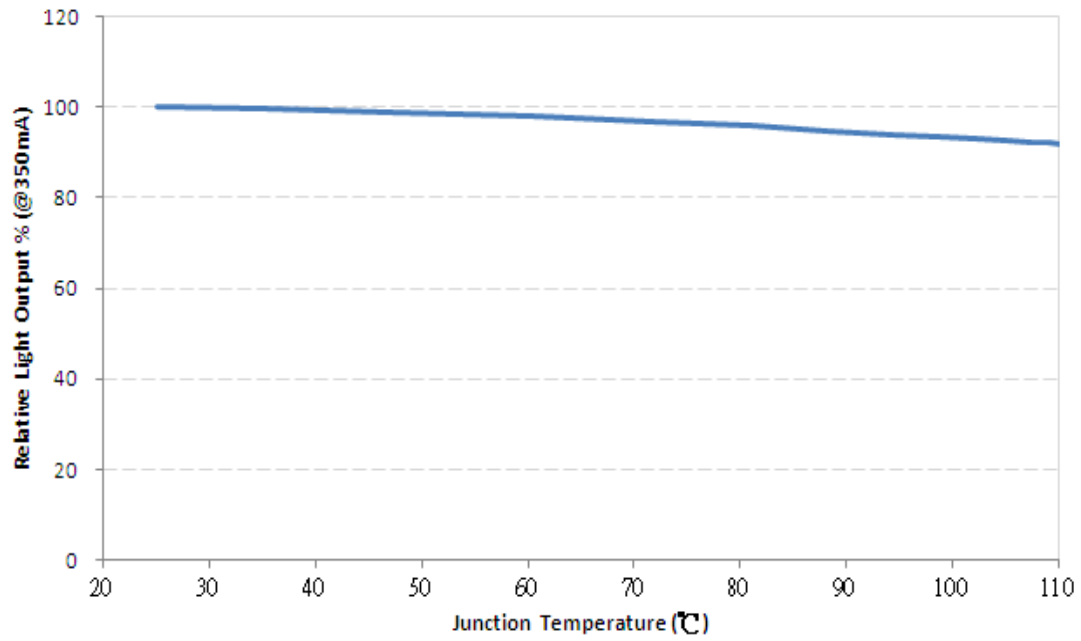
Typical Forward L-I Characteristics, $T_j=25^\circ\text{C}$



Typical Forward I-V Characteristics, $T_j=25^\circ\text{C}$

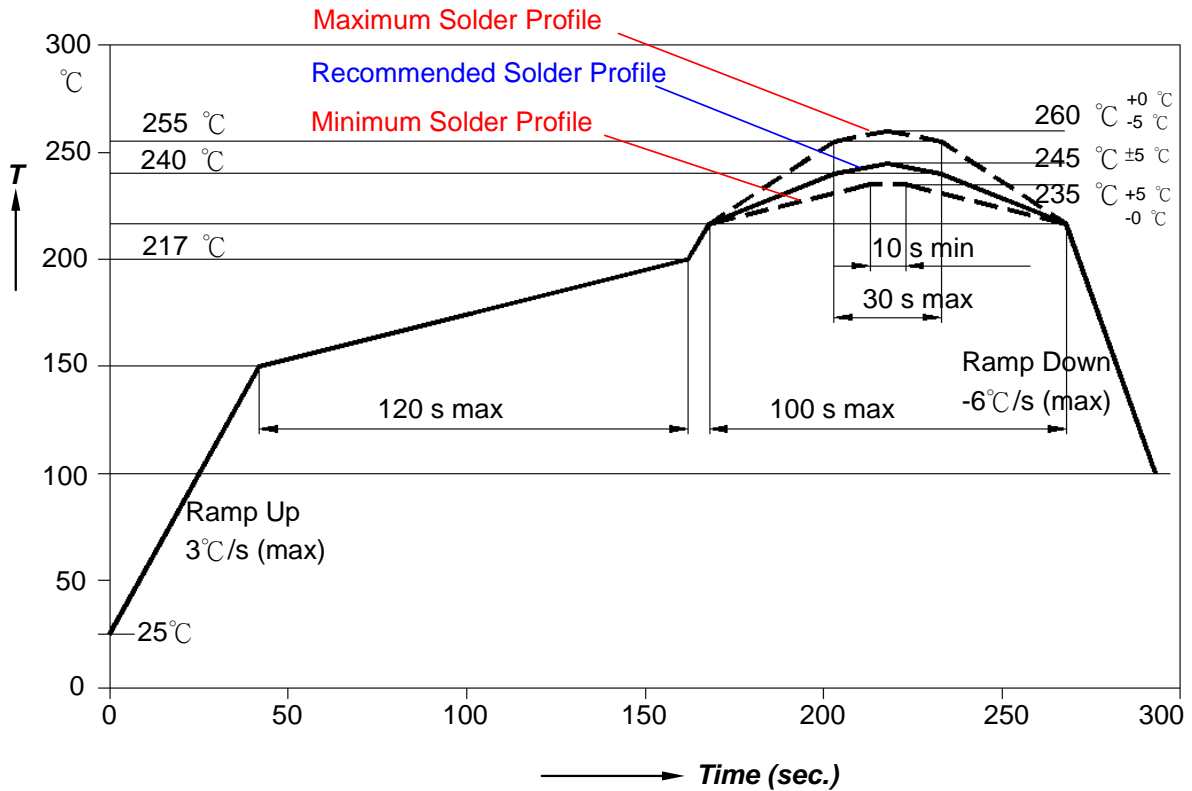


Typical Light Output vs. T_j Characteristics



Recommended Soldering Profile

The LEDs can be soldered using the parameters listed below. As a general guideline, the users are suggested to follow the recommended soldering profile provided by the manufacturer of the solder paste. Although the recommended soldering conditions are specified in the list, reflow soldering at the lowest possible temperature is advised for the LEDs.

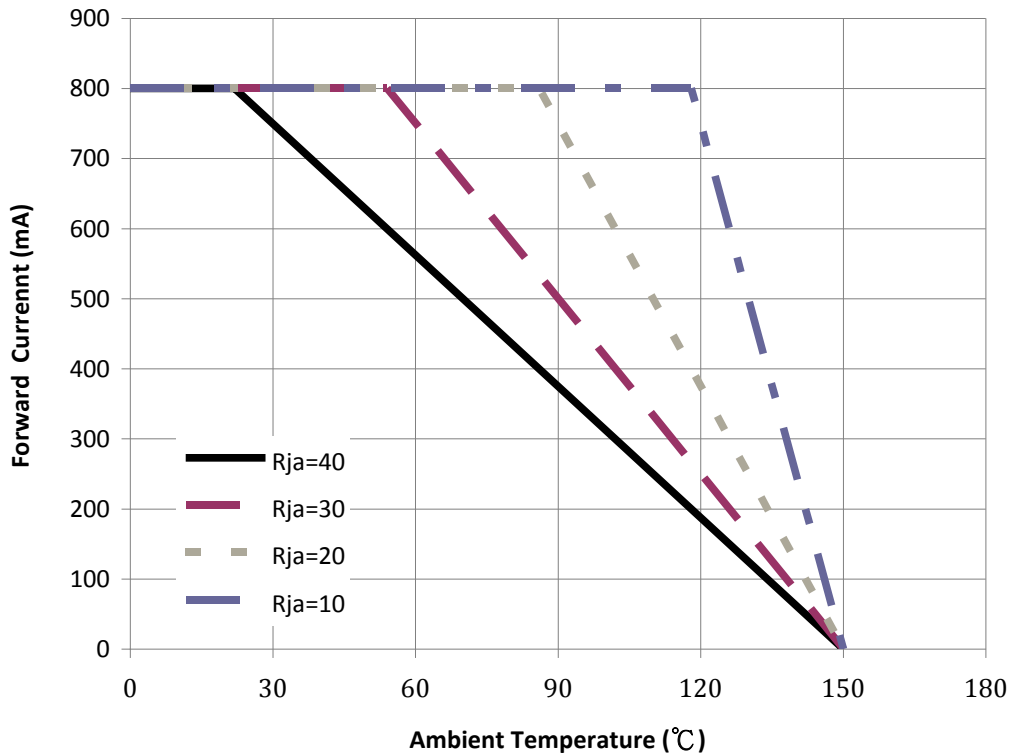


Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-up Rate (T _{Smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
- Temperature Min(T _{Smin})	100°C	150°C
- Temperature Max(T _{Smax})	150°C	200°C
- Time(ts _{min} to ts _{max})	60-120 seconds	60-180 seconds
Time maintained above:		
- Temperature(T _l)	183°C	217°C
- Time(t _l)	60-150 seconds	60-150 seconds
Peak/classification Temperature(T _p)	215°C	260°C
Time within 5°C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



Thermal Design

Thermal design of the end product is important. The thermal resistance between the junction and the solder point ($R_{\theta_{j-p}}$) and the end product should be designed to minimize the thermal resistance from the solder point to ambient in order to optimize the emitter life and optical characteristics. The maximum operation current is determined by the plot of Allowable Forward Current vs. Ambient Temperature.



The junction temperature can be correlated to the thermal resistance between the junction and ambient (R_{ja}) by the following equation.

$$T_j = T_a + R_{ja} * W$$

T_j : LED junction temperature

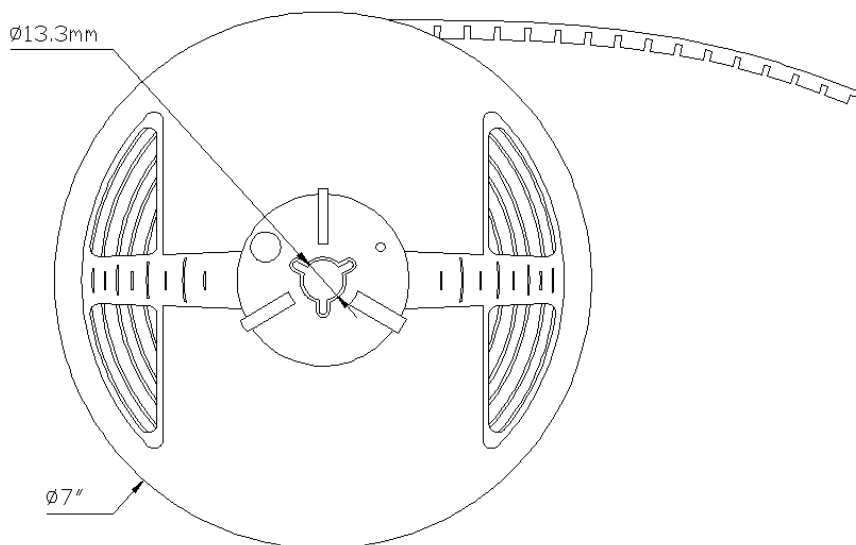
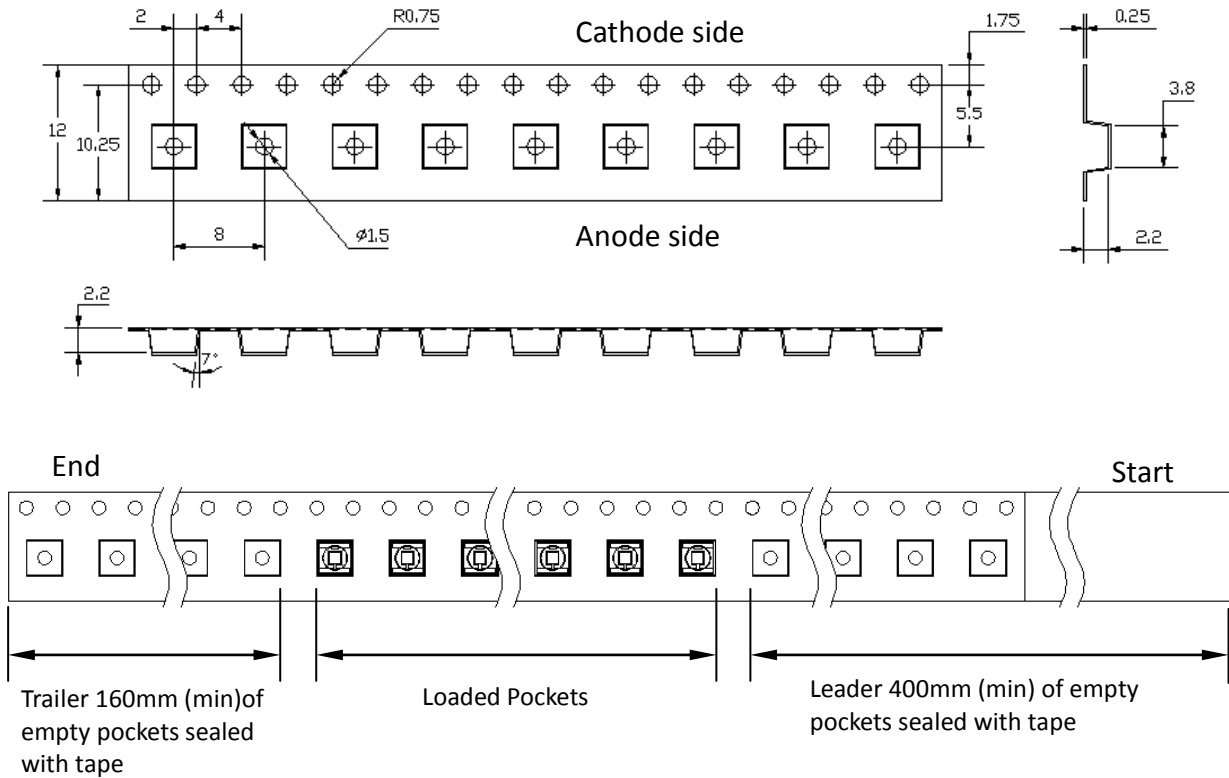
T_a : Ambient temperature

R_{ja} : Thermal resistance between the junction and ambient

W : Input power ($I_F * V_F$)

Packing Information

The carrier tape conform to EIA-481D.



Note:

1. All dimensions are in millimeter.



About Us

Taiwan Semiconductor Lighting Co, Ltd (TSLC) is devoted to developing high-density, and multi-size emitters with powerful output to satisfy the needs of every customer.

Taiwan Semiconductor Lighting Co, Ltd (TSLC) is the leader in LED solutions. Unlimited design flexibility for interior and exterior spaces with high-end lighting effect; energy-efficient for UV curing to improve the quality of medical care; horticulture solutions create a better environment for everyone; high-intensity rotatable lightings for the entertainment industry, TSLC is always there for your lighting needs.

For further company or product information, please visit us at www.tslc.com.tw or please contact sales@tslc.com.tw.



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